

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|--------|---|---|------------------|---------|------------------|
| L1 | 793201 | ((stack stacked stacking stackable) (first second) (top bottom) (upper lower)) with (dice die chip ic semiconductor (integrated adj circuit)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/12/09 11:07 |
| L2 | 404097 | (pad terminal electrode) same wire | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/12/09 11:08 |
| L3 | 27259 | 1 same 2 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/12/09 11:09 |
| L4 | 5669 | ((insulator insulative insulation) (adhesion adhesive)) same 3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/12/09 11:12 |
| L5 | 3384 | (package packaging packaged) and 4 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/12/09 11:12 |
| L6 | 3054 | ((insulator insulative insulation) and (adhesion adhesive)) and 3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/12/09 11:12 |
| L7 | 2339 | (package packaging packaged) and 6 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/12/09 11:12 |
| L8 | 2184 | (substrate carrier board pcb ((printed wiring) adj3 board)) and 7 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/12/09 11:13 |